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Details

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Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	PG-TQFP-48
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc886c-8ffa-5v-ac

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General Device Information

Symbol	Pin Number (TQFP-48/64)	Туре	Reset State	Function			
P5		I/O		Port 5 Port 5 is an 8-bit bidirectional general purpos I/O port. It can be used as alternate functions for UART, UART1 and JTAG.			
P5.0	-/8		PU	EXINT1_1	External Interrupt Input 1		
P5.1	-/9		PU	EXINT2_1	External Interrupt Input 2		
P5.2	-/12		PU	RXD_2	UART Receive Data Input		
P5.3	-/13		PU	TXD_2	UART Transmit Data Output/Clock Output		
P5.4	_/14		PU	RXDO_2	UART Transmit Data Output		
P5.5	-/15		PU	TDO_2 TXD1_2	JTAG Serial Data Output UART1 Transmit Data Output/ Clock Output		
P5.6	-/19		PU	TCK_2 RXDO1_2	JTAG Clock Input UART1 Transmit Data Output		
P5.7	-/20		PU	TDI_2 RXD1_2	JTAG Serial Data Input UART1 Receive Data Input		

Table 3Pin Definitions and Functions (cont'd)



XC886/888CLM

General Device Information

Symbol	Pin Number (TQFP-48/64)	Туре	Reset State	Function
V _{DDP}	7, 17, 43/ 7, 25, 55	-	_	I/O Port Supply (3.3 or 5.0 V) Also used by EVR and analog modules. All pins must be connected.
V _{SSP}	18, 42/26, 54	-	-	I/O Port Ground All pins must be connected.
V _{DDC}	6/6	-	-	Core Supply Monitor (2.5 V)
V _{SSC}	5/5	_	-	Core Supply Ground
V _{AREF}	24/32	_	-	ADC Reference Voltage
V _{AGND}	23/31	_	-	ADC Reference Ground
XTAL1	4/4	I	Hi-Z	External Oscillator Input (backup for on-chip OSC, normally NC)
XTAL2	3/3	0	Hi-Z	External Oscillator Output (backup for on-chip OSC, normally NC)
TMS	10/16	I	PD	Test Mode Select
RESET	41/53	1	PU	Reset Input
MBC ¹⁾	44/58	1	PU	Monitor & BootStrap Loader Control
NC	-/56, 57	_	_	No Connection

Table 3Pin Definitions and Functions (cont'd)

1) An external pull-up device in the range of 4.7 k Ω to 100 k Ω . is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.



3 Functional Description

Chapter 3 provides an overview of the XC886/888 functional description.

3.1 **Processor Architecture**

The XC886/888 is based on a high-performance 8-bit Central Processing Unit (CPU) that is compatible with the standard 8051 processor. While the standard 8051 processor is designed around a 12-clock machine cycle, the XC886/888 CPU uses a 2-clock machine cycle. This allows fast access to ROM or RAM memories without wait state. Access to the Flash memory, however, requires an additional wait state (one machine cycle). The instruction set consists of 45% one-byte, 41% two-byte and 14% three-byte instructions.

The XC886/888 CPU provides a range of debugging features, including basic stop/start, single-step execution, breakpoint support and read/write access to the data memory, program memory and Special Function Registers (SFRs).

Figure 6 shows the CPU functional blocks.



Figure 6 CPU Block Diagram



3.2.4 XC886/888 Register Overview

The SFRs of the XC886/888 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in **Chapter 3.2.4.1** to **Chapter 3.2.4.14**.

Note: The addresses of the bitaddressable SFRs appear in bold typeface.

3.2.4.1 CPU Registers

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP =	0 or 1										
81 _H	SP Reset: 07 _H	Bit Field	eld SP								
	Stack Pointer Register	Туре				r	W				
82 _H	DPL Reset: 00 _H	Bit Field	DPL7	DPL6	DPL5	DPL4	DPL3	DPL2	DPL1	DPL0	
	Data Pointer Register Low	Туре	rw	rw	rw	rw	rw	rw	rw	rw	
83 _H	DPH Reset: 00 _H	Bit Field	DPH7	DPH6	DPH5	DPH4	DPH3	DPH2	DPH1	DPH0	
	Data Pointer Register High	Туре	rw	rw	rw	rw	rw	rw	rw	rw	
87 _H	PCON Reset: 00 _H	Bit Field	SMOD		0		GF1	GF0	0	IDLE	
	Power Control Register	Туре	rw		r		rw	rw	r	rw	
⁸⁸ H	TCON Reset: 00 _H	Bit Field	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	
	Timer Control Register	Туре	rwh	rw	rwh	rw	rwh	rw	rwh	rw	
89 _H	TMOD Reset: 00 _H Timer Mode Register	Bit Field	GATE 1	T1S	T1M		GATE 0	TOS	том		
		Туре	rw	rw	r	W	rw	rw	r	rw	
8A _H	TL0 Reset: 00 _H	Bit Field	VAL								
	Timer 0 Register Low	Туре	rwh								
8B _H	TL1 Reset: 00 _H	Bit Field	VAL								
	Limer 1 Register Low	Туре	rwh								
8C _H	THO Reset: 00 _H	Bit Field	VAL								
	Timer U Register High	Туре	rwh								
8D _H	TH1 Reset: 00 _H	Bit Field	VAL								
	Timer 1 Register High	Туре				n	vh				
98 _H	SCON Reset: 00 _H	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI	
	Serial Channel Control Register	Туре	rw	rw	rw	rw	rw	rwh	rwh	rwh	
99 _H	SBUF Reset: 00 _H	Bit Field				V	AL				
	Serial Data Buffer Register	Туре				rv	vh				
A2 _H	EO Reset: 00 _H Extended Operation Register	Bit Field		0		TRAP_ EN		0		DPSE L0	
		Туре		r		rw		r		rw	

Table 5 CPU Register Overview



Table 8SCU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
вс _Н	NMISR Reset: 00 _H NMI Status Register	Bit Field	0	FNMI ECC	FNMI VDDP	FNMI VDD	FNMI OCDS	FNMI FLASH	FNMI PLL	FNMI WDT
		Туре	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
вd _Н	BCON Reset: 00 _H	Bit Field	d BGSEL 0 BRDIS				BRPRE		R	
	Baud Rate Control Register	Туре	r	w	r	rw		rw		rw
BE _H	BG Reset: 00 _H	Bit Field	BR_VALUE							
	Baud Rate Timer/Reload Register	Туре	rwh							
E9 _H	FDCON Reset: 00 _H Fractional Divider Control	Bit Field	BGS	SYNE N	ERRS YN	EOFS YN	BRK	NDOV	FDM	FDEN
	Register	Туре	rw	rw	rwh	rwh	rwh	rwh	rw	rw
EA _H	FDSTEP Reset: 00 _H	Bit Field				ST	ΈP			
	Register	Туре				r	w			
EB _H	FDRES Reset: 00 _H	Bit Field				RES	SULT			
	Fractional Divider Result Register	Туре				r	h			
RMAP =	= 0, PAGE 1		1							
B3 _H ID Reset: UU _H	Bit Field	PRODID					VERID			
Identity Register		Туре	r					r		
B4 _H	B4 _H PMCON0 Reset: 00 _H Power Mode Control Register 0	Bit Field	0	WDT RST	WKRS	WK SEL	SD	PD	WS	
		Туре	r	rwh	rwh	rw	rw	rwh	rw	
в5 _Н	PMCON1 Reset: 00 _H Power Mode Control Register 1	Bit Field	0	CDC_ DIS	CAN_ DIS	MDU_ DIS	T2_ DIS	CCU_ DIS	SSC_ DIS	ADC_ DIS
		Туре	r	rw	rw	rw	rw	rw	rw	rw
в6 _Н	OSC_CON Reset: 08 _H OSC Control Register	Bit Field	0 OSC PD			OSC PD	XPD	OSC SS	ORD RES	OSCR
		Туре		r		rw	rw	rw	rwh	rh
в7 _Н	PLL_CON Reset: 90 _H PLL Control Register	Bit Field		N	VIV		VCO BYP	OSC DISC	RESL D	LOCK
		Туре		r	W		rw	rw	rwh	rh
ва _Н	CMCON Reset: 10 _H Clock Control Register	Bit Field	VCO SEL	KDIV	0	FCCF G		CLK	REL	
		Туре	rw	rw	r	rw		r	w	
вв _Н	PASSWD Reset: 07 _H Password Register	Bit Field			PASS			PROT ECT_S	MC	DE
		Туре			wh			rh	r	W
вс _Н	FEAL Reset: 00 _H	Bit Field				ECCER	RADDR			
	Low	Туре				r	h			
вd _Н	FEAH Reset: 00 _H	Bit Field				ECCER	RADDR			
	Hash Error Address Register	Туре				r	h			





Figure 18 Interrupt Request Sources (Part 5)



3.7 Reset Control

The XC886/888 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC886/888 is first powered up, the status of certain pins (see **Table 23**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overrightarrow{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9* V_{DDC} . The delay of external reset can be realized by an external capacitor at $\overrightarrow{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* V_{DDC} .

A typical application example is shown in Figure 22. The V_{DDP} capacitor value is 100 nF while the V_{DDC} capacitor value is 220 nF. The capacitor connected to RESET pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9^*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the RESET pin should be held low for 500 µs typically. See Figure 23.



Figure 22 Reset Circuitry



- 1) BSL mode is automatically entered if no valid password is installed and data at memory address 0000H equals zero.
- 2) OSC is bypassed in MultiCAN BSL mode
- 3) Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.

Note: The boot options are valid only with the default set of UART and JTAG pins.

3.8 Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the XC886/888. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL. In the XC886/888, the oscillator can be from either of these two sources: the on-chip oscillator (9.6 MHz) or the external oscillator (4 MHz to 12 MHz). The term "oscillator" is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default. The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.





Figure 24 CGU Block Diagram

PLL Base Mode

When the oscillator is disconnected from the PLL, the system clock is derived from the VCO base (free running) frequency clock (**Table 25**) divided by the K factor.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

(3.1)

Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

(3.2)



3.8.2 Clock Management

The CGU generates all clock signals required within the microcontroller from a single clock, f_{sys} . During normal system operation, the typical frequencies of the different modules are as follow:

- CPU clock: CCLK, SCLK = 24 MHz
- Fast clock (used by MultiCAN): FCLK = 24 or 48 MHz
- Peripheral clock: PCLK = 24 MHz
- Flash Interface clock: CCLK2 = 48 MHz and CCLK = 24 MHz

In addition, different clock frequencies can be output to pin CLKOUT (P0.0 or P0.7). The clock output frequency, which is derived from the clock output divider (bit COREL), can further be divided by 2 using toggle latch (bit TLEN is set to 1). The resulting output frequency has a 50% duty cycle. **Figure 26** shows the clock distribution of the XC886/888.



Figure 26 Clock Generation from f_{sys}



3.9 Power Saving Modes

The power saving modes of the XC886/888 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see **Figure 27**) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode



Figure 27 Transition between Power Saving Modes



3.10 Watchdog Timer

The Watchdog Timer (WDT) provides a highly reliable and secure way to detect and recover from software or hardware failures. The WDT is reset at a regular interval that is predefined by the user. The CPU must service the WDT within this interval to prevent the WDT from causing an XC886/888 system reset. Hence, routine service of the WDT confirms that the system is functioning properly. This ensures that an accidental malfunction of the XC886/888 will be aborted in a user-specified time period.

In debug mode, the WDT is default suspended and stops counting. Therefore, there is no need to refresh the WDT during debugging.

Features

- 16-bit Watchdog Timer
- Programmable reload value for upper 8 bits of timer
- Programmable window boundary
- Selectable input frequency of $f_{PCLK}/2$ or $f_{PCLK}/128$
- Time-out detection with NMI generation and reset prewarning activation (after which a system reset will be performed)

The WDT is a 16-bit timer incremented by a count rate of $f_{\rm PCLK}/2$ or $f_{\rm PCLK}/128$. This 16-bit timer is realized as two concatenated 8-bit timers. The upper 8 bits of the WDT can be preset to a user-programmable value via a watchdog service access in order to modify the watchdog expire time period. The lower 8 bits are reset on each service access. **Figure 28** shows the block diagram of the WDT unit.



Figure 28 WDT Block Diagram



I able J I	able 51 Deviation Error for GART with Fractional Divider enabled									
f _{pclk}	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	STEP	Deviation Error						
24 MHz	1	10 (A _H)	197 (C5 _H)	+0.20 %						
12 MHz	1	6 (6 _H)	236 (EC _H)	+0.03 %						
8 MHz	1	4 (4 _H)	236 (EC _H)	+0.03 %						
6 MHz	1	3 (3 _H)	236 (EC _H)	+0.03 %						

Table 31 Deviation Error for UART with Fractional Divider enabled

3.13.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3 of UART module, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

Mode 1, 3 baud rate=
$$\frac{2^{\text{SMOD}} \times f_{\text{PCLK}}}{32 \times 2 \times (256 - \text{TH1})}$$

(3.7)

3.14 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see **Figure 30**). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV} , where n is defined by 256 - STEP. The output frequency in normal divider mode is derived as follows:

$$f_{MOD} = f_{DIV} \times \frac{1}{256 - STEP}$$

(3.8)



needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data. The break must contain a dominant value of 13 bits or more to ensure proper synchronization of slave nodes.

In the LIN communication, a slave task is required to be synchronized at the beginning of the protected identifier field of frame. For this purpose, every frame starts with a sequence consisting of a break field followed by a synch byte field. This sequence is unique and provides enough information for any slave task to detect the beginning of a new frame and be synchronized at the start of the identifier field.

Upon entering LIN communication, a connection is established and the transfer speed (baud rate) of the serial communication partner (host) is automatically synchronized in the following steps:

STEP 1: Initialize interface for reception and timer for baud rate measurement

STEP 2: Wait for an incoming LIN frame from host

STEP 3: Synchronize the baud rate to the host

- STEP 4: Enter for Master Request Frame or for Slave Response Frame
- Note: Re-synchronization and setup of baud rate are always done for **every** Master Request Header or Slave Response Header LIN frame.



3.16 High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features

- Master and slave mode operation
 - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
 - Programmable number of data bits: 2 to 8 bits
 - Programmable shift direction: LSB or MSB shift first
 - Programmable clock polarity: idle low or high state for the shift clock
 - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
 - On a transmitter empty condition
 - On a receiver full condition
 - On an error condition (receive, phase, baud rate, transmit error)

Data is transmitted or received on lines TXD and RXD, which are normally connected to the pins MTSR (Master Transmit/Slave Receive) and MRST (Master Receive/Slave Transmit). The clock signal is output via line MS_CLK (Master Serial Shift Clock) or input via line SS_CLK (Slave Serial Shift Clock). Both lines are normally connected to the pin SCLK. Transmission and reception of data are double-buffered.

Figure 32 shows the block diagram of the SSC.



- CAN functionality according to CAN specification V2.0 B active.
- Dedicated control registers are provided for each CAN node.
- A data transfer rate up to 1 MBaud is supported.
- Flexible and powerful message transfer control and error handling capabilities are implemented.
- Advanced CAN bus bit timing analysis and baud rate detection can be performed for each CAN node via the frame counter.
- Full-CAN functionality: A set of 32 message objects can be individually
 - allocated (assigned) to any CAN node
 - configured as transmit or receive object
 - setup to handle frames with 11-bit or 29-bit identifier
 - counted or assigned a timestamp via a frame counter
 - configured to remote monitoring mode
- Advanced Acceptance Filtering:
 - Each message object provides an individual acceptance mask to filter incoming frames.
 - A message object can be configured to accept only standard or only extended frames or to accept both standard and extended frames.
 - Message objects can be grouped into 4 priority classes.
 - The selection of the message to be transmitted first can be performed on the basis of frame identifier, IDE bit and RTR bit according to CAN arbitration rules.
- Advanced Message Object Functionality:
 - Message Objects can be combined to build FIFO message buffers of arbitrary size, which is only limited by the total number of message objects.
 - Message objects can be linked to form a gateway to automatically transfer frames between 2 different CAN buses. A single gateway can link any two CAN nodes. An arbitrary number of gateways may be defined.
- Advanced Data Management:
 - The Message objects are organized in double chained lists.
 - List reorganizations may be performed any time, even during full operation of the CAN nodes.
 - A powerful, command driven list controller manages the organization of the list structure and ensures consistency of the list.
 - Message FIFOs are based on the list structure and can easily be scaled in size during CAN operation.
 - Static Allocation Commands offer compatibility with TwinCAN applications, which are not list based.
- Advanced Interrupt Handling:
 - Up to 8 interrupt output lines are available. Most interrupt requests can be individually routed to one of the 8 interrupt output lines.
 - Message postprocessing notifications can be flexibly aggregated into a dedicated register field of 64 notification bits.



3.23 Chip Identification Number

The XC886/888 identity (ID) register is located at Page 1 of address $B3_{H}$. The value of ID register is 09_{H} for Flash devices and 22_{H} for ROM devices. However, for easy identification of product variants, the Chip Identification Number, which is an unique number assigned to each product variant, is available. The differentiation is based on the product, variant type and device step information.

Two methods are provided to read a device's chip identification number:

- In-application subroutine, GET_CHIP_INFO
- Bootstrap loader (BSL) mode A

Table 36 lists the chip identification numbers of available XC886/888 Flash and ROM device variants.

Product Variant	Chip Identification Number								
	AA-Step	AB-Step	AC-Step						
Flash Devices									
XC886CLM-8FFA 3V3	-	09500102 _H	0B500102 _H						
XC888CLM-8FFA 3V3	-	09500103 _H	0B500103 _H						
XC886LM-8FFA 3V3	-	09500122 _H	0B500122 _H						
XC888LM-8FFA 3V3	-	09500123 _H	0B500123 _H						
XC886CLM-6FFA 3V3	-	09551502 _H	0B551502 _H						
XC888CLM-6FFA 3V3	-	09551503 _н	0B551503 _H						
XC886LM-6FFA 3V3	-	09551522 _H	0B551522 _H						
XC888LM-6FFA 3V3	-	09551523 _н	0B551523 _H						
XC886CM-8FFA 3V3	-	09580102 _H	0B580102 _H						
XC888CM-8FFA 3V3	-	09580103 _H	0B580103 _H						
XC886C-8FFA 3V3	-	09580142 _H	0B580142 _H						
XC888C-8FFA 3V3	-	09580143 _H	0B580143 _H						
XC886-8FFA 3V3	-	09580162 _H	0B580162 _H						
XC888-8FFA 3V3	-	09580163 _H	0B580163 _H						
XC886CM-6FFA 3V3	-	095D1502 _H	0B5D1502 _H						
XC888CM-6FFA 3V3	-	095D1503 _H	0B5D1503 _H						
XC886C-6FFA 3V3	-	095D1542 _H	0B5D1542 _H						
XC888C-6FFA 3V3	-	095D1543 _H	0B5D1543 _H						

Table 36 Chip Identification Number



Table 36Chip Identification Number (cont'd)

Product Variant	Chip Identification Number								
	AA-Step	AB-Step	AC-Step						
XC886-6FFA 3V3	-	095D1562 _H	0B5D1562 _H						
XC888-6FFA 3V3	-	095D1563 _H	0B5D1563 _H						
XC886CLM-8FFA 5V	-	09900102 _H	0B900102 _H						
XC888CLM-8FFA 5V	-	09900103 _H	0B900103 _H						
XC886LM-8FFA 5V	-	09900122 _H	0B900122 _H						
XC888LM-8FFA 5V	-	09900123 _H	0B900123 _H						
XC886CLM-6FFA 5V	-	09951502 _H	0B951502 _H						
XC888CLM-6FFA 5V	-	09951503 _н	0B951503 _Н						
XC886LM-6FFA 5V	-	09951522 _н	0B951522 _H						
XC888LM-6FFA 5V	-	09951523 _н	0B951523 _Н						
XC886CM-8FFA 5V	-	09980102 _H	0B980102 _H						
XC888CM-8FFA 5V	-	09980103 _H	0B980103 _H						
XC886C-8FFA 5V	-	09980142 _H	0B980142 _H						
XC888C-8FFA 5V	-	09980143 _H	0B980143 _H						
XC886-8FFA 5V	-	09980162 _H	0B980162 _H						
XC888-8FFA 5V	-	09980163 _н	0B980163 _H						
XC886CM-6FFA 5V	-	099D1502 _H	0B9D1502 _H						
XC888CM-6FFA 5V	-	099D1503 _н	0B9D1503 _H						
XC886C-6FFA 5V	-	099D1542 _H	0B9D1542 _H						
XC888C-6FFA 5V	-	099D1543 _H	0B9D1543 _H						
XC886-6FFA 5V	-	099D1562 _H	0B9D1562 _H						
XC888-6FFA 5V	-	099D1563 _H	0B9D1563 _H						
ROM Devices									
XC886CLM-8RFA 3V3	22400502 _H	-	-						
XC888CLM-8RFA 3V3	22400503 _H	-	-						
XC886LM-8RFA 3V3	22400522 _H	-	-						
XC888LM-8RFA 3V3	22400523 _H	-	-						
XC886CLM-6RFA 3V3	22411502 _H	-	-						
XC888CLM-6RFA 3V3	22411503 _H	-	-						



Electrical Parameters

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins ($V_{\rm SS}$) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Parameter	Symbol		Lir	nit Val	ues	Unit	Test Conditions/
			min.	typ.	max.		Remarks
Analog reference voltage	V _{AREF}	SR	V _{AGND} + 1	V _{DDP}	V _{DDP} + 0.05	V	1)
Analog reference ground	V_{AGND}	SR	V _{SS} - 0.05	V _{SS}	V _{AREF} - 1	V	1)
Analog input voltage range	V_{AIN}	SR	V_{AGND}	_	V_{AREF}	V	
ADC clocks	$f_{\sf ADC}$		-	24	25.8	MHz	module clock ¹⁾
	f _{adci}		_	_	10	MHz	internal analog clock ¹⁾ See Figure 35
Sample time	t _S	CC	$(2 + INPCR0.STC) \times t_{ADCI}$		μS	1)	
Conversion time	t _C	CC	See Se	ection	4.2.3.1	μS	1)
Total unadjusted	TUE	CC	-	-	1	LSB	8-bit conversion ²⁾
error			-	-	2	LSB	10-bit conversion ²⁾
Differential Nonlinearity	$ EA_{DNL} $	СС	_	1	-	LSB	10-bit conversion ¹⁾
Integral Nonlinearity	EA _{INL}	CC	_	1	_	LSB	10-bit conversion ¹⁾
Offset	$ EA_{OFF} $	CC	-	1	-	LSB	10-bit conversion ¹⁾
Gain	$ EA_{GAIN} $	CC	_	1	-	LSB	10-bit conversion ¹⁾
Overload current coupling factor for	K _{OVA}	СС	_	_	1.0 x 10 ⁻⁴	_	$I_{\rm OV} > 0^{1)3)}$
analog inputs			_	_	1.5 x 10 ⁻³	_	$I_{\rm OV} < 0^{1)3)}$

Table 40ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)



Electrical Parameters

4.3.2 Output Rise/Fall Times

Table 45 provides the characteristics of the output rise/fall times in the XC886/888.

Table 45 Output Rise/Fall Times Parameters (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Conditions	
		min.	min. max.			
V_{DDP} = 5V Range						
Rise/fall times	t _R , t _F	_	10	ns	20 pF. ¹⁾²⁾³⁾	
V _{DDP} = 3.3V Range						
Rise/fall times	t _R , t _F	-	10	ns	20 pF. ¹⁾²⁾⁴⁾	
					1	

1) Rise/Fall time measurements are taken with 10% - 90% of pad supply.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) Additional rise/fall time valid for $C_{\rm L}$ = 20pF - 100pF @ 0.125 ns/pF.

4) Additional rise/fall time valid for $C_{\rm L}$ = 20pF - 100pF @ 0.225 ns/pF.



Figure 43 Rise/Fall Times Parameters